RoHS Compliant
HALOGEN-FREE

Magnachip

MDD3N50G

N-Channel MOSFET 500V, 2.8 A, 2.5Ω

General Description

The MDD3N50G uses advanced Magnachip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent quality.

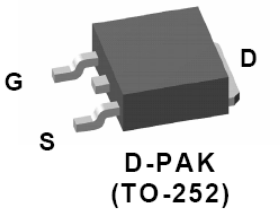
MDD3N50G is suitable device for SMPS, HID and general purpose applications.

Features

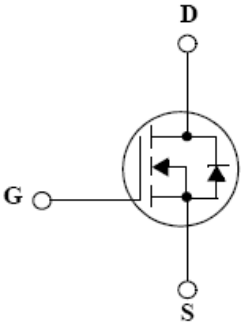
- V_{DS} = 500V
- I_D = 2.8A @V_{GS} = 10V
- $R_{DS(ON)}$ ≤ 2.5Ω @V_{GS} = 10V

Applications

- Power Supply
- PFC
- Ballast



D-PAK
(TO-252)



Absolute Maximum Ratings (Ta = 25ºC)

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	500	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current	T_C=25ºC	I_D	2.8	A
	T_C=100ºC		1.7	A
Pulsed Drain Current(1)		I_{DM}	11.2	A
Power Dissipation	T_C=25ºC	P_D	45	W
	Derate above 25 °C		0.36	W/ °C
Peak Diode Recovery dV/dt(3)		dV/dt	4.5	V/ns
MOSFET dV/dt		dV/dt	50	V/ns
Repetitive Pulse Avalanche Energy(4)		E_{AR}	4.5	mJ
Single Pulse Avalanche Energy(4)		E_{AS}	170	mJ
Junction and Storage Temperature Range		T_J, T_{stg}	-55~150	°C

Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient(1)	$R_{\theta JA}$	110	ºC/W
Thermal Resistance, Junction-to-Case(1)	$R_{\theta JC}$	2.75	

Ordering Information

Part Number	Temp. Range	Package	Packing	RoHS Status
MDD3N50GRH	-55~150°C	D-PAK (TO-252)	Reel	Halogen Free

Electrical Characteristics (Ta =25°C)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	I_D = 250μA, V_{GS} = 0V	500	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	3.0	-	5.0	
Drain Cut-Off Current	I_{DSS}	V_{DS} = 500V, V_{GS} = 0V	-	-	1	μA
Gate Leakage Current	I_{GSS}	V_{GS} = ±30V, V_{DS} = 0V	-	-	100	nA
Drain-Source ON Resistance	$R_{DS(ON)}$	V_{GS} = 10V, I_D = 1.4A		2.1	2.5	Ω
Forward Transconductance	g_{fs}	V_{DS} = 30V, I_D = 1.4A	-	4.8	-	S
Dynamic Characteristics						
Total Gate Charge	Q_g	V_{DS} = 400V, I_D = 3A, V_{GS} = 10V(3)	-	6.75	-	nC
Gate-Source Charge	Q_{gs}		-	2	-	
Gate-Drain Charge	Q_{gd}		-	2.6	-	
Input Capacitance	C_{iss}	V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz	-	285	-	pF
Reverse Transfer Capacitance	C_{rss}		-	1.6	-	
Output Capacitance	C_{oss}		-	25	-	
Turn-On Delay Time	$t_{d(on)}$	V_{GS} = 10V, V_{DS} = 250V, I_D = 3A, R_G = 25Ω(3)	-	19	-	ns
Rise Time	t_r		-	22	-	
Turn-Off Delay Time	$t_{d(off)}$		-	33	-	
Fall Time	t_f		-	20	-	
Drain-Source Body Diode Characteristics						
Maximum Continuous Drain to Source Diode Forward Current	I_S		-	-	2.8	A
Source-Drain Diode Forward Voltage	V_{SD}	I_S = 2.8A, V_{GS} = 0V	-		1.4	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 3.0A, dI/dt = 100A/μs(3)	-	190		ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	0.9		μC

Note :

1. Pulse width is based on R θJC & R θJA and the maximum allowed junction temperature of 150°C.
2. Pulse test: pulse width ≤300us, duty cycle≤2%, pulse width limited by junction temperature TJ(MAX)=150°C.
3. I_{SD} ≤3.0A, di/dt≤200A/us, V_{DD}=50V, R_g =25Ω, Starting TJ=25°C
4. L=40mH, I_{AS}=2.8A, V_{DD}=50V, , R_g =25Ω, Starting TJ=25°C

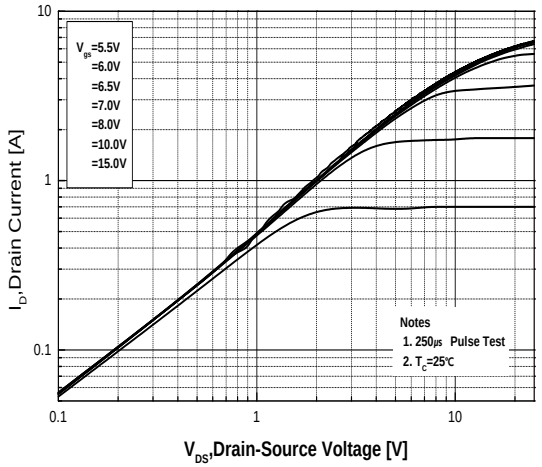


Fig.1 On-Region Characteristics

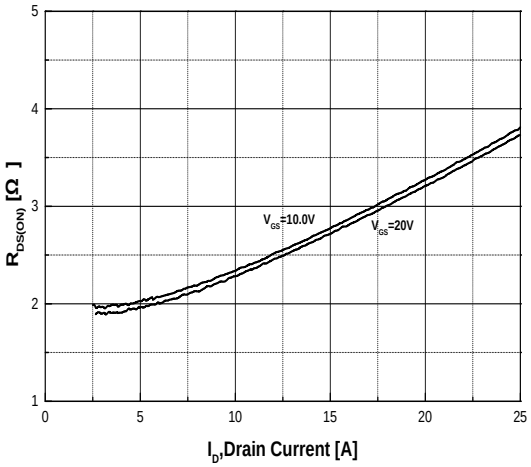


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

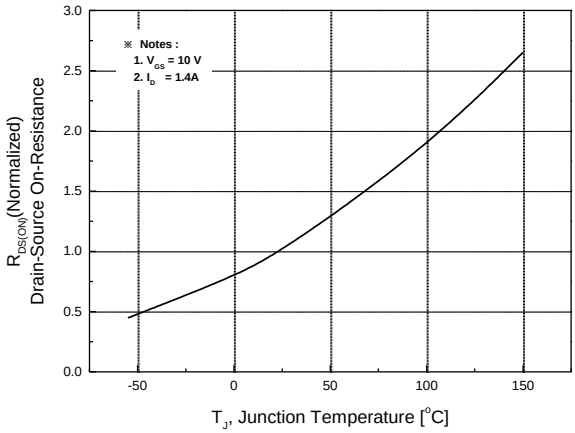


Fig.3 On-Resistance Variation with Temperature

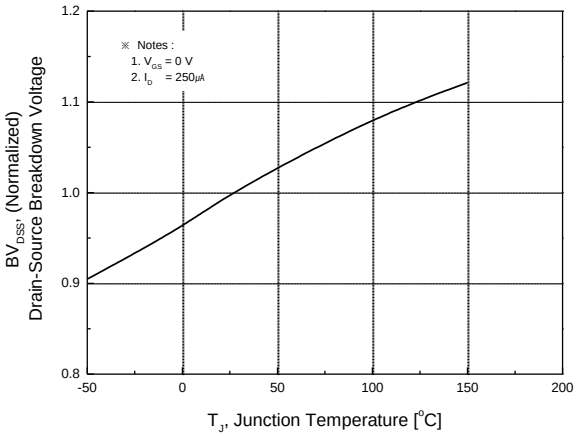


Fig.4 Breakdown Voltage Variation vs. Temperature

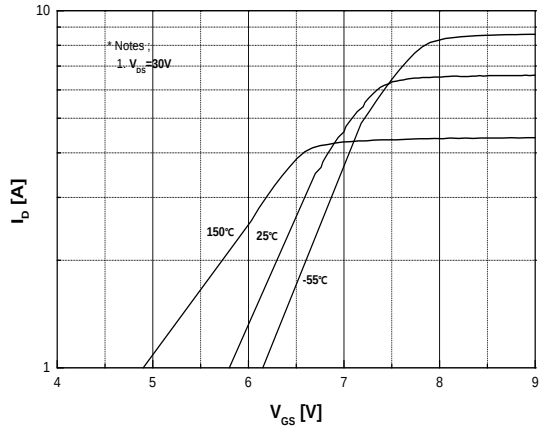


Fig.5 Transfer Characteristics

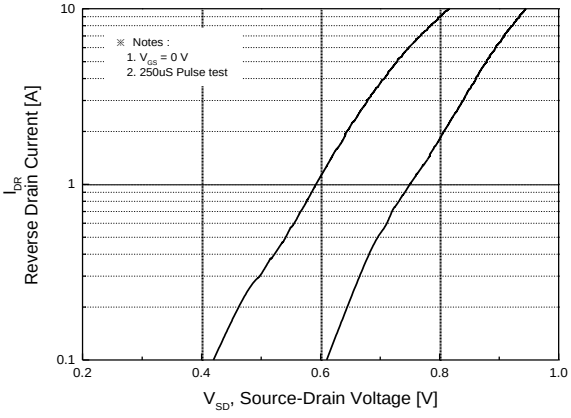


Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature

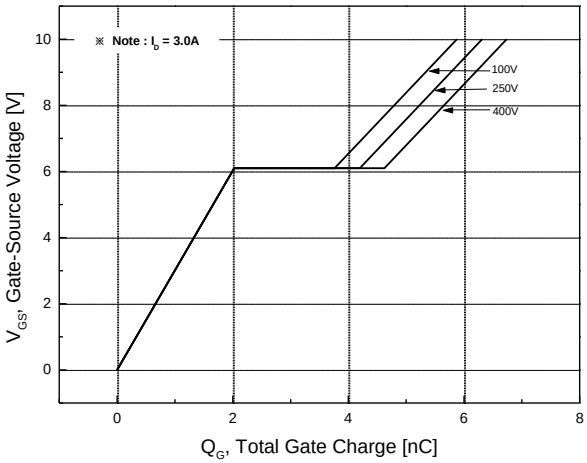


Fig.7 Gate Charge Characteristics

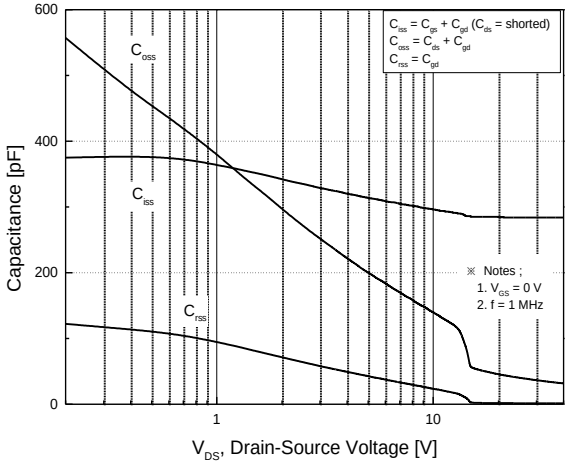


Fig.8 Capacitance Characteristics

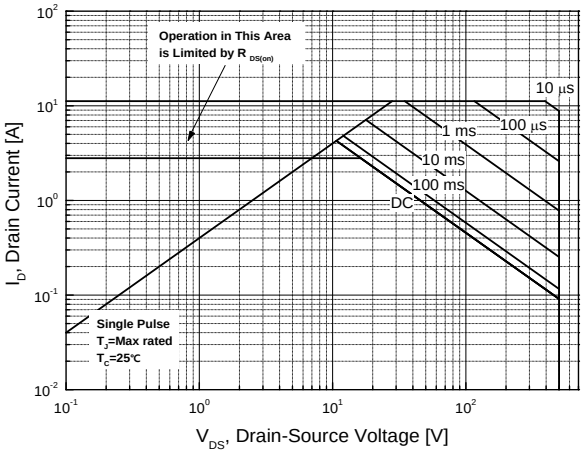


Fig.9 Maximum Safe Operating Area

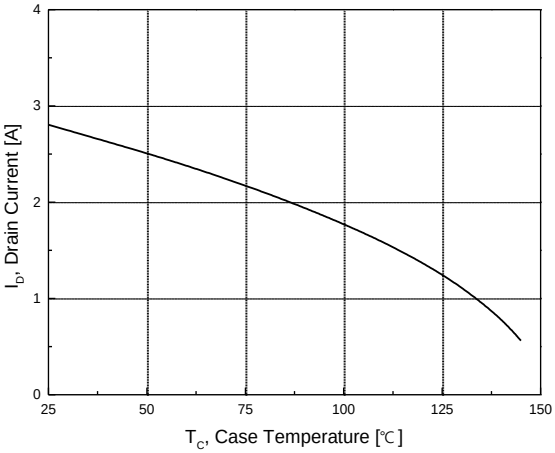


Fig.10 Maximum Drain Current vs. Case Temperature

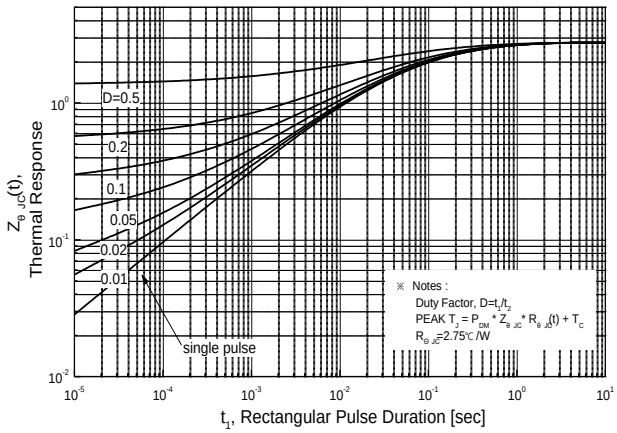


Fig.11 Transient Thermal Response Curve

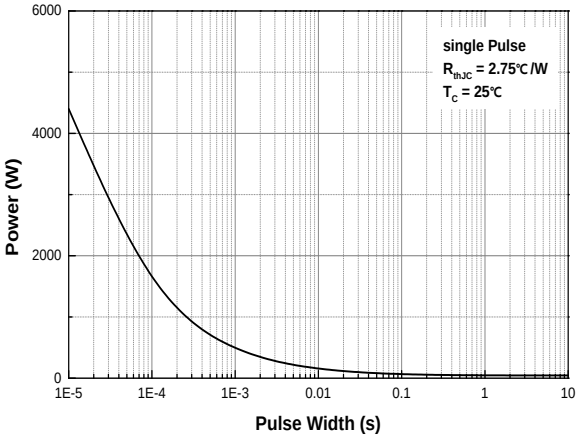
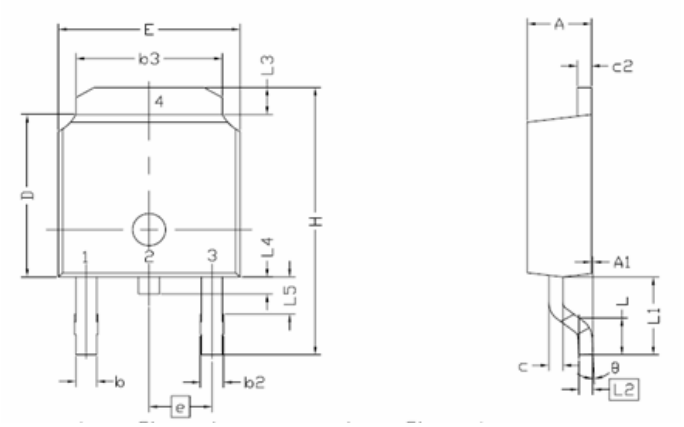


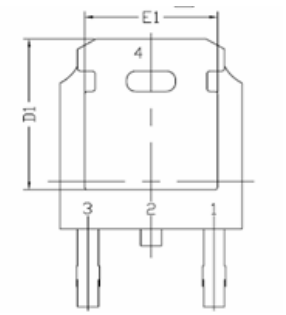
Fig.12 Single Pulse Maximum Power Dissipation

Physical Dimension

D-PAK, 3L

Dimensions are in millimeters, unless otherwise specified





Symbol	Min.	Nom.	Max.
E	6.35	-	6.73
L	1.40	1.52	1.78
L1		2.74 REF	
L2		0.508 BCS	
L3	0.89	-	1.27
L4	-	-	1.02
L5	1.14	-	1.52
D	5.97	6.10	6.22
H	9.40	-	10.41
b	0.64	-	0.89
b2	0.76	-	1.14
b3	4.95	-	5.46
e		2.286 BSC	
A	2.18	-	2.39
A1	-	-	0.13
c	0.46	-	0.61
c2	0.46	-	0.89
D1	5.21	-	-
E1	4.32	-	-
θ	0.00	-	10.00

Note : Package body size, length and width do not include mold flash, protrusions and gate burrs.

DISCLAIMER:

The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.

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